IGBT

This Insulated Gate Bipolar Transistor (IGBT) features a robust and cost effective Field Stop (FS) Trench construction, and provides superior performance in demanding switching applications. Offering both low on-state voltage and minimal switching loss, the IGBT is well suited for resonant or soft switching applications. Incorporated into the device is a rugged co-packaged free wheeling diode with a low forward voltage.

Features

- Low Saturation Voltage using Trench with Field Stop Technology
- Low Switching Loss Reduces System Power Dissipation
- Low Gate Charge
- 5 µs Short-Circuit Capability
- These are Pb-Free Devices

Typical Applications

- Inverter Welding Machines
- Microwave Ovens
- Industrial Switching
- Motor Control Inverter

ABSOLUTE MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector-emitter voltage	V_{CES}	1200	V
Collector current @ Tc = 25°C @ Tc = 100°C	I _C	60 30	A
Pulsed collector current, T _{pulse} limited by T _{Jmax}	I _{CM}	240	Α
Diode forward current @ Tc = 25°C @ Tc = 100°C	I _F	60 30	A
Diode pulsed current, T _{pulse} limited by T _{Jmax}	I _{FM}	240	Α
Gate-emitter voltage	V_{GE}	±20	V
Power Dissipation @ Tc = 25°C @ Tc = 100°C	P _D	560 224	W
Short–Circuit Withstand Time $V_{GE} = 15 \text{ V}, V_{CE} = 600 \text{ V}, T_J \le 150^{\circ}\text{C}$	T _{sc}	5	μs
Operating junction temperature range	TJ	-55 to +150	°C
Storage temperature range	T _{stg}	-55 to +150	°C
Lead temperature for soldering, 1/8" from case for 5 seconds	T _{SLD}	260	°C

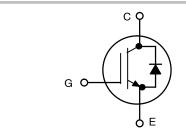
Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

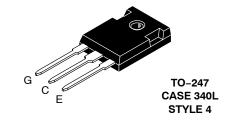


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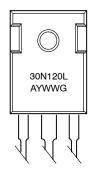
http://onsemi.com

30 A, 1200 V V_{CEsat} = 1.75 V E_{off} = 1.0 mJ





MARKING DIAGRAM



A = Assembly Location

Y = Year WW = Work Week G = Pb-Free Package

ORDERING INFORMATION

Device	Package	Shipping
NGTB30N120LWG	TO-247 (Pb-Free)	30 Units / Rail

THERMAL CHARACTERISTICS

Rating	Symbol	Value	Unit
Thermal resistance junction-to-case, for IGBT	$R_{ heta JC}$	0.223	°C/W
Thermal resistance junction-to-case, for Diode	$R_{ heta JC}$	1.5	°C/W
Thermal resistance junction-to-ambient	$R_{ heta JA}$	40	°C/W

ELECTRICAL CHARACTERISTICS ($T_J = 25^{\circ}C$ unless otherwise specified)

Parameter	Test Conditions	Symbol	Min	Тур	Max	Unit
STATIC CHARACTERISTIC						
Collector-emitter breakdown voltage, gate-emitter short-circuited	$V_{GE} = 0 \text{ V, } I_{C} = 500 \mu\text{A}$	V _{(BR)CES}	1200	-	_	V
Collector-emitter saturation voltage	V _{GE} = 15 V, I _C = 30 A V _{GE} = 15 V, I _C = 30 A, T _J = 150°C	V _{CEsat}	1.35 -	1.75 2.1	2.2 -	V
Gate-emitter threshold voltage	$V_{GE} = V_{CE}$, $I_C = 400 \mu A$	V _{GE(th)}	4.5	5.5	6.5	V
Collector-emitter cut-off current, gate- emitter short-circuited	V _{GE} = 0 V, V _{CE} = 1200 V V _{GE} = 0 V, V _{CE} = 1200 V, T _{J =} 150°C	I _{CES}	- -	- -	0.5 2.0	mA
Gate leakage current, collector-emitter short-circuited	V _{GE} = 20 V, V _{CE} = 0 V	I _{GES}	_	_	100	nA
DYNAMIC CHARACTERISTIC		•				-
Input capacitance		C _{ies}	-	10,400	-	pF
Output capacitance	V _{CE} = 20 V, V _{GE} = 0 V, f = 1 MHz	C _{oes}	-	245	-	1
Reverse transfer capacitance	1	C _{res}	-	185	-	1
Gate charge total		Qg	-	420	-	nC
Gate to emitter charge	V _{CE} = 600 V, I _C = 30 A, V _{GE} = 15 V	Q _{ge}	-	94	-	
Gate to collector charge		Q _{gc}	-	178	-	
SWITCHING CHARACTERISTIC, INDUC	TIVE LOAD					
Turn-on delay time		t _{d(on)}	-	136	-	
Rise time	1	t _r	-	36	-	1
Turn-off delay time	$T_J = 25^{\circ}C$ $V_{CC} = 600 \text{ V, } I_C = 30 \text{ A}$	t _{d(off)}	-	360	-	ns
Fall time	$R_g = 10 \Omega$ $V_{GE} = 0 \text{ V} / 15 \text{ V}$	t _f	-	150	_	
Turn-on switching loss	VGE = 0 V/ 13 V	E _{on}	-	4.4	=	I
Turn-off switching loss	1	E _{off}	-	1.0	_	mJ
Turn-on delay time		t _{d(on)}	_	131	_	
Rise time	T 40500	t _r	-	36	_]
Turn-off delay time	$T_J = 125^{\circ}C$ $V_{CC} = 600 \text{ V, } I_C = 30 \text{ A}$	t _{d(off)}	-	380	_	ns
Fall time	$R_g = 10 \Omega$ $V_{GE} = 0 \text{ V} / 15 \text{ V}$	t _f	-	216	=	
Turn-on switching loss	VGE - 0 V/ 13 V	E _{on}	-	5.3	-	I
Turn-off switching loss		E _{off}	-	2.0	-	mJ
DIODE CHARACTERISTIC						
Forward voltage	V _{GE} = 0 V, I _F = 30 A V _{GE} = 0 V, I _F = 30 A, T _J = 150°C	V _F	- -	1.5 1.7	1.7 -	V

TYPICAL CHARACTERISTICS

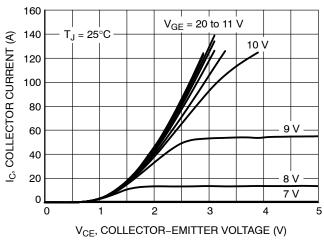


Figure 1. Output Characteristics

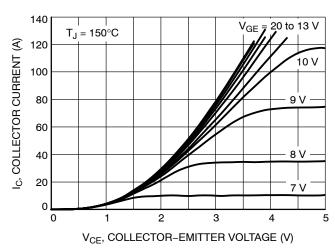


Figure 2. Output Characteristics

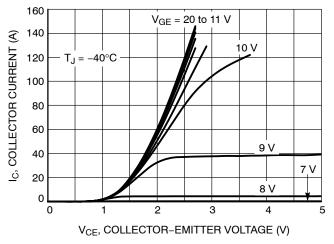


Figure 3. Output Characteristics

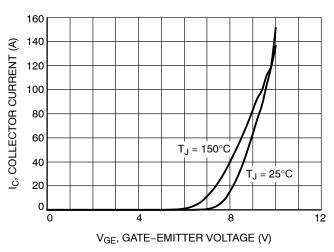


Figure 4. Typical Transfer Characteristics

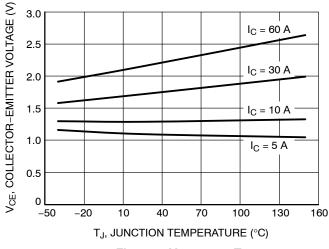


Figure 5. V_{CE(sat)} vs. T_J

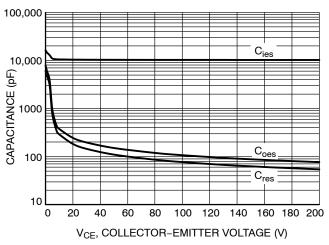


Figure 6. Typical Capacitance

TYPICAL CHARACTERISTICS

20

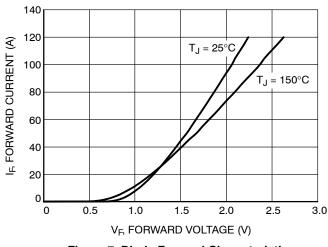
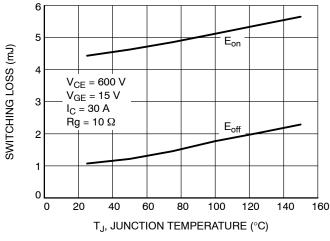


Figure 7. Diode Forward Characteristics

Figure 8. Typical Gate Charge



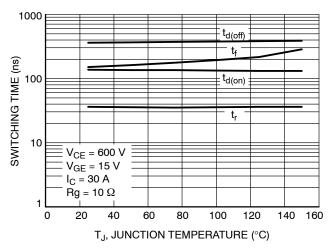
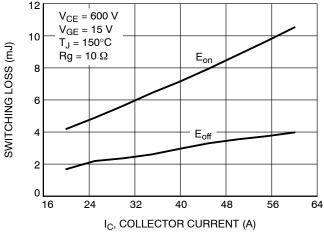


Figure 9. Switching Loss vs. Temperature

Figure 10. Switching Time vs. Temperature



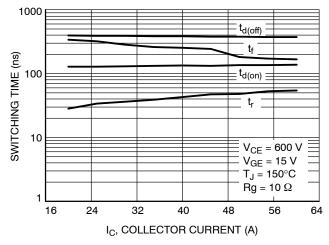
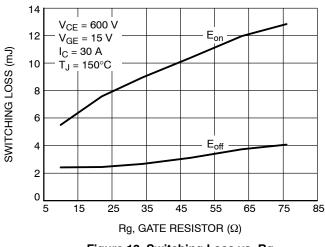


Figure 11. Switching Loss vs. I_C

Figure 12. Switching Time vs. I_C

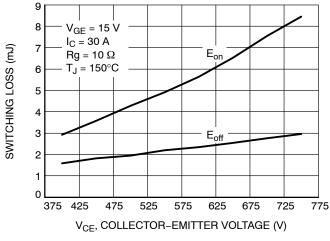
TYPICAL CHARACTERISTICS



10,000 SWITCHING TIME (ns) 100 10 $t_{d(off)}$ t_f $t_{d(on)}$ t_r V_{CE} = 600 V V_{GE} = 15 V I_C = 30 A T_J = 150°C 5 15 25 35 45 55 65 Rg, GATE RESISTOR (Ω)

Figure 13. Switching Loss vs. Rg

Figure 14. Switching Time vs. Rg



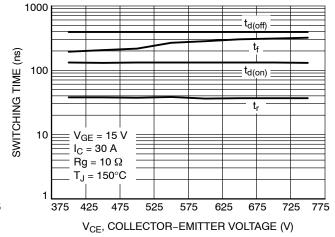
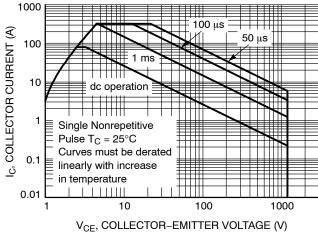


Figure 15. Switching Loss vs. V_{CE}

Figure 16. Switching Time vs. V_{CE}



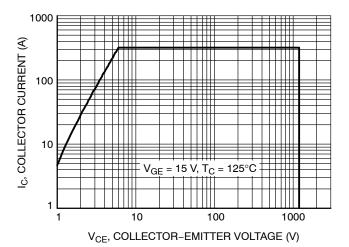


Figure 17. Safe Operating Area

Figure 18. Reverse Bias Safe Operating Area

TYPICAL CHARACTERISTICS

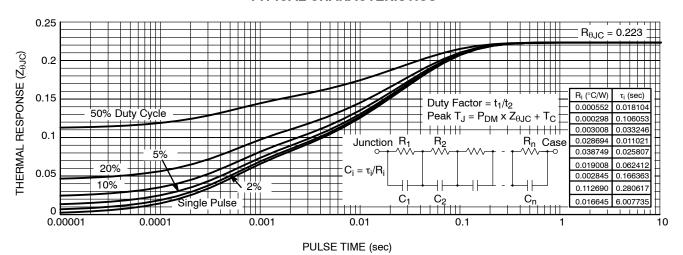


Figure 19. IGBT Transient Thermal Impedance

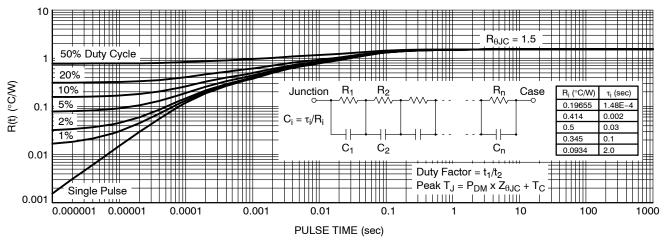


Figure 20. Diode Transient Thermal Impedance

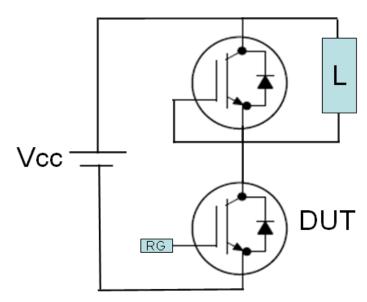


Figure 21. Test Circuit for Switching Characteristics

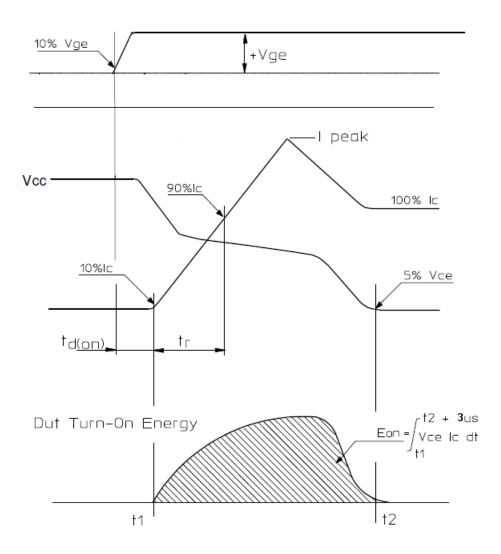


Figure 22. Definition of Turn On Waveform

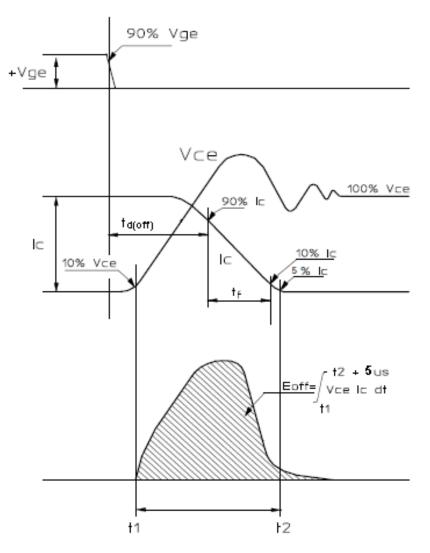
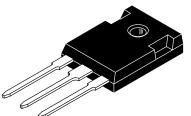


Figure 23. Definition of Turn Off Waveform





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DATE 06 OCT 2021

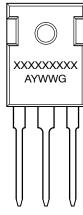
- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: MILLIMETER

	MILLIMETERS		INC	HES
DIM	MIN.	MAX.	MIN.	MAX.
Α	20.32	21.08	0.800	0.830
В	15.75	16.26	0.620	0.640
С	4.70	5.30	0.185	0.209
D	1.00	1.40	0.040	0.055
Ε	1.90	2.60	0.075	0.102
F	1.65	2.13	0.065	0.084
G	5.45 BSC		0.215 BSC	
I	1.50	2.49	0.059	0.098
J	0.40	0.80	0.016	0.031
K	19.81	20.83	0.780	0.820
١	5.40	6.20	0.212	0.244
N	4.32	5.49	0.170	0.216
Ρ		4.50		0.177
Q	3.55	3.65	0.140	0.144
٦	6.15	BSC	0.242	BSC
W	2.87	3.12	0.113	0.123

NOTES:

SCALE 1:1 Α øΩ 2X F 3X D

GENERIC MARKING DIAGRAM*



STYLE 1: PIN 1. GATE 2. DRAIN 3. SOURCE 4. DRAIN

PIN 1. CATHODE 2. ANODE

3. GATE 4. ANODE

STYLE 5:

STYLE 2: PIN 1. ANODE 2. CATHODE (S) 3. ANODE 2 4. CATHODES (S)

PIN 1. MAIN TERMINAL 1 2. MAIN TERMINAL 2

3. GATE 4. MAIN TERMINAL 2

STYLE 6:

♦0.25 (0.010)**₩** Y AS

STYLE 3: PIN 1. BASE 2. COLLECTOR 3. EMITTER 4. COLLECTOR STYLE 4: PIN 1. GATE 2. COLLECTOR 3. EMITTER 4. COLLECTOR

XXXXX = Specific Device Code = Assembly Location Α

Υ = Year WW = Work Week = Pb-Free Package G

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

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